EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L4	7	input adj device with display adj device with CPU with system and "257"/$.ccls.	USPAT	OR	ON	2006/02/25 11:36
L5	0	input adj device with display adj device with CPU with system same interface and "257"/$.ccls.	USPAT	OR	ON	2006/02/25 11:36
L6	0	input adj device with display adj device with CPU with system same interfaced and "257"/$.ccls.	USPAT	OR	ON	2006/02/25 11:36
L7	1	input adj device with display adj device with CPU with system same interfaced	USPAT	OR	ON	2006/02/25 11:36
S1	1325	(257/704).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/24 12:26
S2	959	(257/707).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/24 12:26
S3	215	S1 and heat with (lid cover)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/24 16:08
S4	160	S1 and heat with (lid cover)	USPAT	OR	ON	2006/02/24 12:26
S5	39	("20040012939" | "4082394" | "5166772" | "5357404" | "5490040" | "5561265" | "5566052" | "5639989" | "5703397" | "5745344" | "5748455" | "5753857" | "5804872" | "5825634" | "6008536" | "6057600" | "6063999" | "6088231" | "6137051" | "6140577" | "6198630" | "6239359" | "6252313" | "6259609" | "6269863" | "6278617" | "6288330" | "6294731" | "6324074" | "6362477" | "6400164" | "6455925" | "6483406" | "6515870" | "6518660" | "6573590" | "6597575" | "6683796" | "6703704").PN. OR ("6956285"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/24 14:39
S6	4	("5151771" | "5172303" | "5739581" | "5963430").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/24 14:48
S7	4	("5539253").URPN.	USPAT	OR	ON	2006/02/24 14:52

EAST Search History

S8	192	S1 and conductive with (lid cover)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/24 14:58
S9	157	S1 and conductive with (lid cover)	USPAT	OR	ON	2006/02/24 14:54
S10	76	S9 not S4	USPAT	OR	ON	2006/02/24 14:54
S11	35	S8 not S9	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/24 14:58
S12	55	S3 not S4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/24 15:01
S13	38	S12 not S11	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/24 15:01
S14	2	"20050127489".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/24 15:44
S15	41	S1 and substrate with cavity with lid	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/24 16:12
S16	4	("20030042598" | "20040036183" | "6317326" | "6665187").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/24 16:09
S17	0	S1 and interposer with cavity with lid	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/24 16:11
S18	0	S1 and bard with cavity with lid	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/24 16:11

S19	0	S2 and bard with cavity with lid	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/24 16:11
S20	3	S2 and board with cavity with lid	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/24 16:11
S21	5	S1 and board with cavity with lid	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/24 16:11
S22	2081	(257/686).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/24 16:12
S23	8	S22 and substrate with cavity with lid	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/24 16:12
S24	127	S22 and substrate with cavity	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/24 16:12
S25	52	("4574331" | "4581675" | "4764846" | "5007841" | "5027191" | "5043794" | "5241456" | "5376825" | "5432681").PN. OR ("5701233"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/24 16:40
S26	538	(257/710).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/24 16:40
S27	406	S26 and (lid cap cover)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/24 16:41

S28	58	S27 and (substrate interposer board support) with cavity	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/24 16:45
S29	58	S27 and (substrate interposer board support) with cavity	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/24 16:45
S30	64	S26 and (substrate interposer board support) with cavity	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/24 16:45
S31	6	S30 not S29	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/24 16:45
S32	505	((ic integrated near1 circuit microelectronic chip die wafer semiconductor) near2 package)with within with cavity	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/24 18:31
S33	119	((ic integrated near1 circuit microelectronic chip die wafer semiconductor) near2 package)with within with cavity with substrate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/24 17:58
S34	115	S33 not S30	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/24 16:47
S35	43	("5266912" | "5491362" | "5552596" | "5591959" | "5608262" | "5656856" | "5734199" | "5760478" | "5783870" | "5801448" | "5804882" | "5869894" | "5909057" | "5949135" | "5963429" | "5963430" | "5973930" | "5977640" | "6002178" | "6005292" | "6014316" | "6025648" | "6057598" | "6084308" | "6181008").PN. OR ("6369448"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/24 16:50

S36	8	("20030148554"| "5910682"| "6081028"| "6265771"| "6339254"| "6369448"| "6590281"| "6665187"). PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/24 16:52
S37	1	"6965163".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/24 16:53
S38	0	"6794748".p[n.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/24 16:53
S39	1	"6794748".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/24 16:53
S40	4	("5910682"| "6265771"| "6339254" | "6665187").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/24 16:54
S41	31	("5977640"| "6127726"| "6137164" | "6147401"| "6150724").PN. OR ("6339254").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/24 16:54
S42	0	("6794748").URPN.	USPAT	OR	ON	2006/02/24 16:55
S43	23	("3777221"| "5375042"| "5477933" | "5535101").PN. OR ("5973930"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/24 16:57
S44	11	("5222014"| "5614766"| "5712769" | "5801072"| "5847936"| "5973930" | "5994166"| "6150724"| "6239385" | "6294407").PN. OR ("6665194"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/24 16:58
S45	6	("4733461"| "5040992"| "5259784" | "5575686").PN. OR ("5712769"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/24 16:59
S46	15	("20030205826"| "5138436"| "5786979"| "6150724"| "6222276"| "6225699"| "6228682"| "6274214"| "6281042"| "6313998"| "6369444"| "6369448"| "6400008"| "6413353"| "6418029").PN. OR ("6873035"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/24 17:02
S47	2	("6740980").URPN.	USPAT	OR	ON	2006/02/24 17:03
S48	2	("6740980").URPN.	USPAT	OR	ON	2006/02/24 17:04
S49	40	((ic integrated near1 circuit microelectronic chip die wafer semiconductor) near2 package)with within with cavity near2 substrate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/24 18:00
S50	104154	((ic integrated near1 circuit microelectronic chip die wafer semiconductor) near2 package) and package within with cavity near2 substrate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/24 18:01

S51	73	((ic integrated near1 circuit microelectronic chip die wafer semiconductor) near2 package) and package with within with cavity near2 substrate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/24 18:01
S52	33	S51 not S49	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/24 18:03
S53	8	and$1j$2.xa. and socket	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/24 18:03
S54	64	("3326726" | "3337838" | "3366915" | "3444506" | "3848221" | "4274700" | "4487463" | "4530002" | "4572604" | "4616406" | "4654472" | "4655526" | "4667220" | "4698663" | "4724472" | "4734042" | "4820207" | "4897055" | "4943846" | "4959750" | "4970577" | "4975066" | "4997376" | "5015207" | "5037311" | "5071363" | "5081563" | "5106461" | "5110760" | "5117069" | "5123164" | "5137456" | "5200357" | "5281151" | "5309024" | "5326936" | "5330372" | "5334279" | "5342999" | "5351393" | "5371404" | "5376825" | "5390412" | "5418471" | "5508556" | "5536362" | "5569955" | "5575688" | "5578870" | "5593322" | "5611884" | "5634821" | "5639247" | "5641309" | "5645433" | "5646442" | "5702255" | "5824950" | "5854512" | "6097086").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/24 18:05
S55	14	(US-20050073054-$).did. or (US-6956285-$ or US-6856013-$ or US-5285012-$ or US-6861292-$ or US-6339254-$ or US-6876066-$ or US-6777794-$ or US-6665194-$ or US-5712769-$ or US-6558978-$ or US-6873035-$ or US-5611884-$ or US-5786628-$).did.	US-PGPUB; USPAT	OR	ON	2006/02/24 18:10
S56	1	S55 and radu	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/24 18:10

S57	14	(US-20050073054-$).did. or (US-6956285-$ or US-6856013-$ or US-5285012-$ or US-6861292-$ or US-6339254-$ or US-6876066-$ or US-6777794-$ or US-6665194-$ or US-5712769-$ or US-6558978-$ or US-6873035-$ or US-5611884-$ or US-5786628-$).did.	US-PGPUB; USPAT	OR	ON	2006/02/24 18:31
S58	18	((ic integrated near1 circuit microelectronic chip die wafer semiconductor) near2 package).ab. and board with bump with socket	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/24 18:34
S59	60	((ic integrated near1 circuit microelectronic chip die wafer semiconductor) near2 package).ab. and mother adj board with bump	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/24 18:34
S60	2	jp-2000136979-$.did.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/25 09:47
S61	2	jp-2001319997-$.did.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/25 09:47